

CLAIMS

1. A semiconductor integrated circuit including:
pads, and
wirings which are electrically connected to the pads,
wherein said wirings are connected to bumps of a probe card,
in an area other than an area where the pads are disposed.

2. A semiconductor integrated circuit as defined in Claim 1
wherein
at least two of said wirings contact one of said bumps
without being in touch with each other.

3. A semiconductor integrated circuit as defined in Claim 2
wherein
each of said wirings has at least one bent portion or angular
portion.

4. A semiconductor integrated circuit as defined in Claim 2
wherein
said wirings have separable portions.